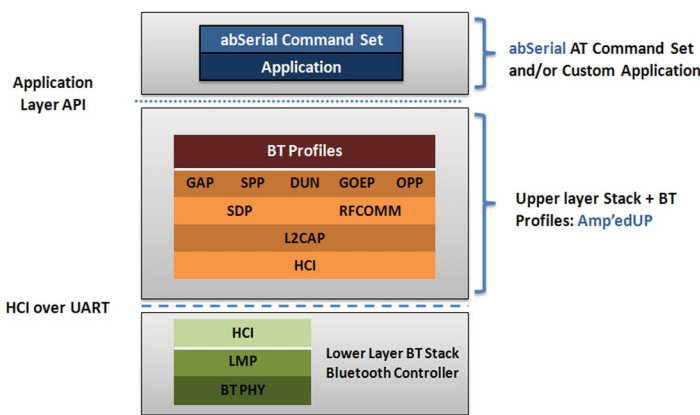


Amp'ed UP

The *Amp'ed UP* software is a complete Bluetooth upper layer protocol stack, covering from the HCI layer up to the Bluetooth profiles: HCI, L2CAP, RFCOMM, SDP, GAP + profiles. Our standard profile offering is the Serial Port Profile, SPP. Optional profiles are OBEX OPP/BIP/GOEP, DUN, HSP/HFP, and HID.

The *Amp'ed UP* stack is ported to ST Microelectronics' ARM 7 and ARM Cortex series of processors. Fully featured, the memory footprint is only 140K Flash and 40K RAM. At its minimum, the size may be as small as 80k Flash and 12K RAM for lower data rate applications.



Licensing Options

- License our designs and Bluetooth Software
- Pre-loaded components
- A one-time fee and modest per unit license
- No modules are required - you control the BOM cost with a "board down" design

Software Development Kit, SDK

- Stack layers are provided as libraries
- Customers may develop applications into the ST Microelectronics' ARM processors
- Support the IAR "C" compiler
- We can supply modules pre-loaded with your application images.

abSerial

Bluetooth modules come standard with our powerful and flexible *abSerial* firmware. Controlling the module through any terminal software program is simple with ASCII AT-style commands.

Bond	EraseBondTable	RemoteCmdDisconnect
Bypass	ExitPart	Reset
ChangeBaud	ExitSniff	Security
ChangeDefaultBaud	GPIOConfig	SmartCableSetup
DefaultLocalName	GPIORead	Sniff
DeleteSmartCable	GPIOWrite	SPPConnect
DisableBond	Hold	SPPDisconnect
Discovery	HostEvent	StreamingSerial
DunConnect	LocalName	UpdateInquiryScan
DunDisconnect	Park	UpdatePageScan
EnableBond	RemoteCommand	Version